Low-Voltage CMOS Octal Buffer

With 5 V–Tolerant Inputs and Outputs (3–State, Non–Inverting)

The MC74LCX244 is a high performance, non-inverting octal buffer operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX244 inputs to be safely driven from 5 V devices. The MC74LCX244 is suitable for memory address driving and all TTL level bus oriented transceiver applications.

Current drive capability is 24 mA at the outputs. The Output Enable (\overline{OE}) input, when HIGH, disables the output by placing them in a HIGH Z condition.

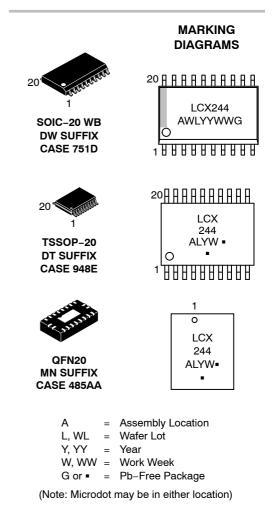
Features

- Designed for 2.3 to 3.6 V V_{CC} Operation
- 5 V Tolerant Interface Capability With 5 V TTL Logic
- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0 V$
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance:
 - ♦ Human Body Model >2000 V
 - Machine Model >200 V
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



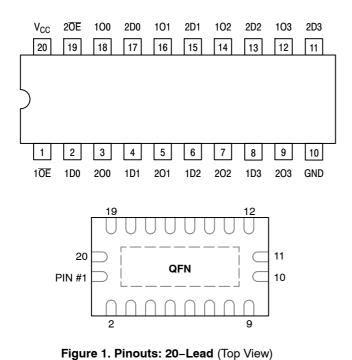
ON Semiconductor®

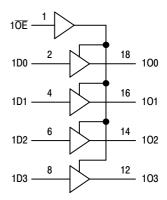
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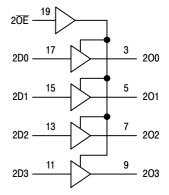


ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.







PINS	FUNCTION	
nOE	Output Enable Inputs	
1Dn, 2Dn	Data Inputs	
10n, 20n	3-State Outputs	

TRUTH TABLE

PIN NAMES

INP	UTS	OUTPUTS
1 <u>0E</u> 20E	1Dn 2Dn	10n, 20n
L	L	L
L	Н	Н
Н	Х	Z

H = High Voltage Level L = Low Voltage Level

Z = High Impedance State

X = High or Low Voltage Level and Transitions are Acceptable

For I_{CC} reasons, DO NOT FLOAT Inputs

Figure 2. Logic Diagram

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Units
V _{CC}	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_I \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \le V_O \le +7.0$	Output in 3-State	V
		$-0.5 \leq V_O \leq V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Ι _Ο	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	–65 to +150		°C
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds	T _L = 260		°C
TJ	Junction Temperature Under Bias	T _J = 150		°C
θ_{JA}	Thermal Resistance (Note 2)	θ _{JA} = 140		°C/W
MSL	Moisture Sensitivity		Level 1	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

I_O absolute maximum rating must be observed.
 Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Units
V _{CC}	Supply Voltage Operating Data Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	3.6 3.6	V
VI	Input Voltage	0		5.5	V
V _O	Output Voltage HIGH or LOW State 3-State	0 0		V _{CC} 5.5	V
I _{ОН}	$ HIGH Level Output Current \\ V_{CC} = 3.0 V - 3.6 V \\ V_{CC} = 2.7 V - 3.0 V $			-24 -12	mA
I _{OL}	$ LOW Level Output Current \\ V_{CC} = 3.0 V - 3.6 V \\ V_{CC} = 2.7 V - 3.0 V $			24 12	mA
T _A	Operating Free-Air Temperature	-55		+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, V _{IN} from 0.8 V to 2.0 V, V _{CC} = 3.0 V	0		10	ns/V

DC ELECTRICAL CHARACTERISTICS

			T _A = −55°C	to +125°C	
Symbol	Characteristic	Condition	Min	Мах	Units
VIH	HIGH Level Input Voltage (Note 3)	$2.3~\text{V} \leq \text{V}_{CC} \leq 2.7~\text{V}$	1.7		V
		$2.7 \text{ V} \leq \text{V}_{CC} \leq 3.6 \text{ V}$	2.0		
V _{IL}	LOW Level Input Voltage (Note 3)	$2.3~\text{V} \leq \text{V}_{CC} \leq 2.7~\text{V}$		0.7	V
		$2.7~\text{V} \leq \text{V}_{CC} \leq 3.6~\text{V}$		0.8	
V _{OH}	HIGH Level Output Voltage	2.3 V \leq V_{CC} \leq 3.6 V; I_{OL} = 100 μA	V _{CC} – 0.2		V
		$V_{CC} = 2.3 \text{ V}; \text{ I}_{OH} = -8 \text{ mA}$	1.8		
		$V_{CC} = 2.7 \text{ V}; \text{ I}_{OH} = -12 \text{ mA}$	2.2		
		$V_{CC} = 3.0 \text{ V}; \text{ I}_{OH} = -18 \text{ mA}$	2.4		
		$V_{CC} = 3.0 \text{ V}; \text{ I}_{OH} = -24 \text{ mA}$	2.2		
V _{OL}	LOW Level Output Voltage	$2.3~V \leq V_{CC} \leq 3.6~V;~I_{OL} = 100~\mu A$		0.2	V
		V _{CC} = 2.3 V; I _{OL} = 8 mA		0.6	
		V_{CC} = 2.7 V; I_{OL} = 12 mA		0.4	
		V_{CC} = 3.0 V; I_{OL} = 16 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	
I _{OZ}	3-State Output Current	$\label{eq:VCC} \begin{array}{l} V_{CC} = 3.6 \ \text{V}, \ V_{IN} = V_{IH} \ \text{or} \ V_{IL}, \\ V_{OUT} = 0 \ \text{to} \ 5.5 \ \text{V} \end{array}$		±5	μΑ
I _{OFF}	Power Off Leakage Current	V_{CC} = 0, V_{IN} = 5.5 V or V_{OUT} = 5.5 V		10	μA
I _{IN}	Input Leakage Current	V_{CC} = 3.6 V, V_{IN} = 5.5 V or GND		±5	μA
I _{CC}	Quiescent Supply Current	V_{CC} = 3.6 V, V_{IN} = 5.5 V or GND		10	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	$2.3 \leq V_{CC} \leq 3.6 \text{ V}; \text{ V}_{IH} = V_{CC} - 0.6 \text{ V}$		500	μΑ

3. These values of V₁ are used to test DC electrical characteristics only.

AC CHARACTERISTICS (t_R = t_F = 2.5 ns; R_L = 500 Ω)

					Lim	nits			
					$T_A = -55^{\circ}C$	to +125°C			1
			V _{CC} = 3.0	V to 3.6 V	V _{CC} =	2.7 V	V _{CC} = 2.	5 V \pm 0.2	1
			C _L = 5	50 pF	C _L = \$	50 pF	C _L = 3	30 pF	1
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Units
t _{PLH} t _{PHL}	Propagation Delay Input to Output	1	1.5 1.5	6.5 6.5	1.5 1.5	7.5 7.5	1.5 1.5	7.8 7.8	ns
t _{PZH} t _{PZL}	Output Enable Time to High and Low Level	2	1.5 1.5	8.0 8.0	1.5 1.5	9.0 9.0	1.5 1.5	10 10	ns
t _{PHZ} t _{PLZ}	Output Disable Time From High and Low Level	2	1.5 1.5	7.0 7.0	1.5 1.5	8.0 8.0	1.5 1.5	8.4 8.4	ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 4)			1.0 1.0					ns

4. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

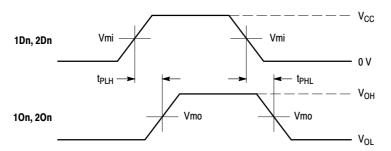
DYNAMIC SWITCHING CHARACTERISTICS

			Т	A = +25°C	2	
Symbol	Characteristic	Condition	Min	Тур	Max	Units
V _{OLP}	Dynamic LOW Peak Voltage (Note 5)			0.8 0.6		V
V _{OLV}	Dynamic LOW Valley Voltage (Note 5)			-0.8 -0.6		V

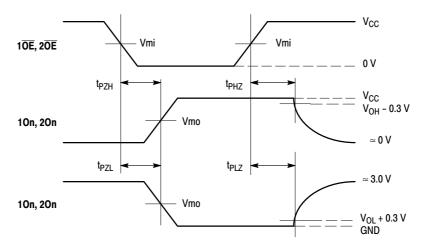
5. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	7	pF
C _{OUT}	Output Capacitance	V_{CC} = 3.3 V, V_I = 0 V or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	25	pF



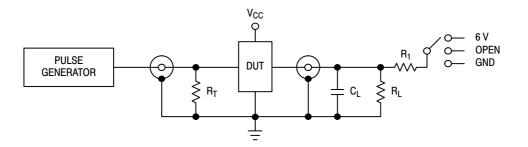
WAVEFORM 1 – PROPAGATION DELAYS $t_{R} = t_{F} = 2.5 \text{ ns}, 10\% \text{ to } 90\%; \text{ f} = 1 \text{ MHz}; t_{W} = 500 \text{ ns}$



WAVEFORM 2 – OUTPUT ENABLE AND DISABLE TIMES t_R = t_F = 2.5 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

Figure 3. AC Waveforms

	V _{CC}			
Symbol	3.3 V \pm 0.3 V	2.7 V	2.5 V \pm 0.2 V	
Vmi	1.5 V	1.5 V	V _{CC} /2	
Vmo	1.5 V	1.5 V	V _{CC} /2	
V _{HZ}	V _{OL} + 0.3 V	V _{OL} + 0.3 V	V _{OL} + 0.15 V	
V_{LZ}	V _{OH} – 0.3 V	V _{OH} – 0.3 V	V _{OH} – 015 V	



TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6 V at V _{CC} = 3.3 ± 0.3 V 6 V at V _{CC} = 2.5 ± 0.2 V
Open Collector/Drain t _{PLH} and t _{PHL}	6 V
t _{PZH} , t _{PHZ}	GND

 C_L = 50 pF at V_{CC} = 3.3 ± 0.3 V or equivalent (includes jig and probe capacitance) C_L = 30 pF at V_{CC} = 2.5 ± 0.2 V or equivalent (includes jig and probe capacitance) R_L = R_1 = 500 Ω or equivalent

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

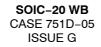
Figure 4. Test Circuit

ORDERING INFORMATION

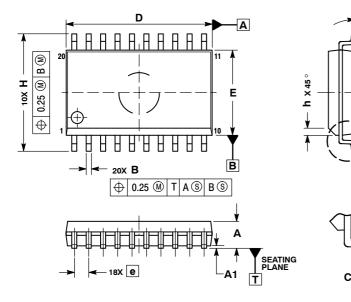
Device	Package	Shipping [†]
MC74LCX244DWG	SOIC-20 WB (Pb-Free)	38 Units / Rail
MC74LCX244DWR2G	SOIC-20 WB (Pb-Free)	1000 / Tape & Reel
MC74LCX244DTG	TSSOP-20 (Pb-Free)	75 Units / Rail
MC74LCX244DTR2G	TSSOP-20 (Pb-Free)	2500 / Tape & Reel
MC74LCX244MNTWG	QFN20 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



f

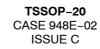


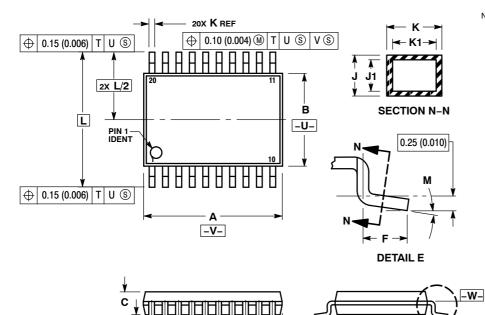
NOTES:

- NOTES:
 DIMENSIONS ARE IN MILLIMETERS.
 INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		
DIM	MIN	MAX	
Α	2.35	2.65	
A1	0.10	0.25	
В	0.35	0.49	
С	0.23	0.32	
D	D 12.65		
E	7.40	7.60	
е	1.27	BSC	
н	10.05	10.55	
h	0.25	0.75	
L	0.50	0.90	
θ	0 °	7 °	

PACKAGE DIMENSIONS





- G

н - NOTES:

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010 PER SIDE. SHALL NOT EXCEED 0.25 (0.010) PER SIDE. 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL

CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR

REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

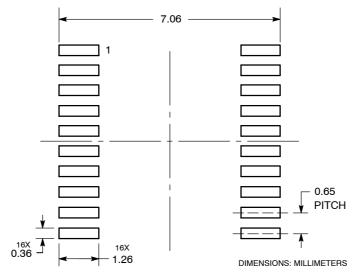
DETERMINED AT DATUM PLANE -W				
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
М	0°	8°	0°	8°

○ 0.100 (0.004)

D

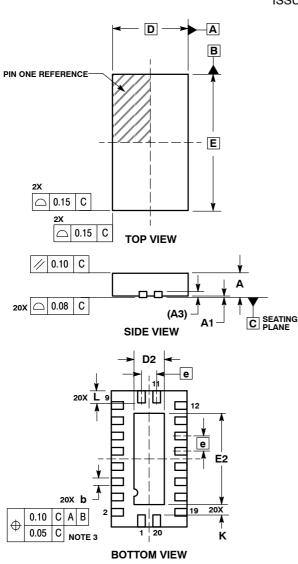
SOLDERING FOOTPRINT

DETAIL E



PACKAGE DIMENSIONS

QFN20, 2.5x4.5 MM CASE 485AA ISSUE B



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
- 0.25 AND 0.30 MM FROM TERMINAL.4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1	0.00	0.05	
A3	0.20 REF		
b	0.20	0.30	
D	2.50 BSC		
D2	0.85	1.15	
E	4.50 BSC		
E2	2.85	3.15	
e	0.50 BSC		
K	0.20		
L	0.35	0.45	

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